



APPLICABLE STANDARD		△			
RATING	OPERATING TEMPERATURE RANGE	△ -40 °C TO 105 °C	STORAGE TEMPERATURE RANGE	-40 °C TO 105 °C (MOUNTED ON PCB)	
	VOLTAGE	50 V AC / DC	OPERATING OR STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 90 % MAX (NOT DEWED)	
	CURRENT	0.5 A (note 1)	APPLICABLE CABLE	t=0.3±0.05mm, GOLD PLATING	
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	×
MARKING		CONFIRMED VISUALLY.			×
ELECTRICAL CHARACTERISTICS					
CONTACT RESISTANCE		1mA(DC OR 1000Hz).		50 mΩ MAX. INCLUDING FPC,FPC BULK RESISTANCE (L=8mm)	×
INSULATION RESISTANCE		100 V DC.		500 MΩ MIN.	×
VOLTAGE PROOF		150 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	×
MECHANICAL CHARACTERISTICS					
MECHANICAL OPERATION		20 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 50 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×
VIBRATION		FREQUENCY 10 TO 55 Hz, HALF AMPLITUDE 0.75 mm, FOR 10 CYCLES IN 3 AXIAL DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② CONTACT RESISTANCE: 50 mΩ MAX.	×
SHOCK		981 m/s <sup>2</sup> , DURATION OF PULSE 6 ms AT 3 TIMES IN 3 BOTH AXIAL DIRECTIONS.		③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×
FPC RETENTION FORCE		MEASURED BY APPLICABLE FPC. (CONNECTOR,FPC AT INITIAL CONDITION. THICKNESS OF FPC SHALL BE t=0.30mm )		DIRECTION OF INSERTION: 0.4xn N MIN ( n : NUMBER OF CONTACTS).	×
ENVIRONMENTAL CHARACTERISTICS					
RAPID CHANGE OF TEMPERATURE △		TEMPERATURE -40→+15TO+35→+105→+15TO+35°C TIME 30→ 2 TO 3 → 30→ 2 TO 3 min. UNDER 5 CYCLES.		① CONTACT RESISTANCE: 50 mΩ MAX. ② INSULATION RESISTANCE: 50 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, RELATIVE HUMIDITY 90 TO 95 %, 96 h.			×
DAMP HEAT,CYCLIC		EXPOSED AT -10 TO +65 °C, RELATIVE HUMIDITY 90 TO 96 %, 10 CYCLES,TOTAL 240 h.		① CONTACT RESISTANCE: 50 mΩ MAX. ② INSULATION RESISTANCE: 1 MΩ MIN. (AT HIGH HUMIDITY) ③ INSULATION RESISTANCE: 50 MΩ MIN. (AT DRY) ④ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×
DRY HEAT △		EXPOSED AT 105±2 °C, 96 h.		① CONTACT RESISTANCE: 50 mΩ MAX.	×
COLD		EXPOSED AT -40±3°C, 96 h.		② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×
CORROSION SALT MIST		EXPOSED AT 35±2 °C 5% SALT WATER SPRAY FOR 96 h.		① CONTACT RESISTANCE: 50 mΩ MAX. ② NO EVIDENCE OF CORROSION WHICH AFFECTS TO OPERATION OF CONNECTOR.	×
SULPHUR DIOXIDE [JIS C 60068-2-42]		EXPOSED AT 40±2 °C , RELATIVE HUMIDITY 80±5% , 25±5 ppm FOR 96 h.			×
HYDROGEN SULPHIDE [JIS C 60068-2-43]		EXPOSED AT 40±2 °C , RELATIVE HUMIDITY 80±5% , 10 TO 15 ppm FOR 96 h.			×
COUNT	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
△ 5	DIS-F-00000202		HK. KINOUCHI	HS. SAKAMOTO	15. 03. 25
REMARK			APPROVED	NF. MIYAZAKI	15. 03. 04
STORAGE TEMPERATURE RANGE IN THE EMBOSSED CARRIER TAPE : -10 TO +50 °C △			CHECKED	SJ. OKAMURA	15. 03. 03
			DESIGNED	HK. KINOUCHI	15. 03. 03
Unless otherwise specified, refer to JIS C 5402.			DRAWN	HK. KINOUCHI	15. 03. 03
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-359845-00-00
HRS	SPECIFICATION SHEET		PART NO.	FH52E-*(*) SB-1SH	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL580	△ 1/2

SPECIFICATIONS					
ITEM	TEST METHOD	REQUIREMENTS	QT	AT	
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING (TO BE 2 TIMES MAX.) PEAK TMP. 250 °C MAX REFLOW TMP. OVER 230 °C WITHIN 60 sec. PRE-HEATING. 150 TO 200°C 90 TO 120 sec. 2)SOLDERING IRONS : 350 ± 10 °C, FOR 5± 1 sec .	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	×	—	
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 245±3 °C FOR IMMERSION DURATION, 3±0.3 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	×	—	
<p>(note 1)</p> <p>WHEN THE SAME VALUE OF CURRENT ARE APPLIED TO ALL CONTACTS AT THE SAME TIME IN ONCE, SET THE CURRENT TO THE 70 % OF THE RATED CURRENT VALUE.</p>					
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	HIROSE ELECTRIC CO., LTD.	CODE NO	CL580		2/2